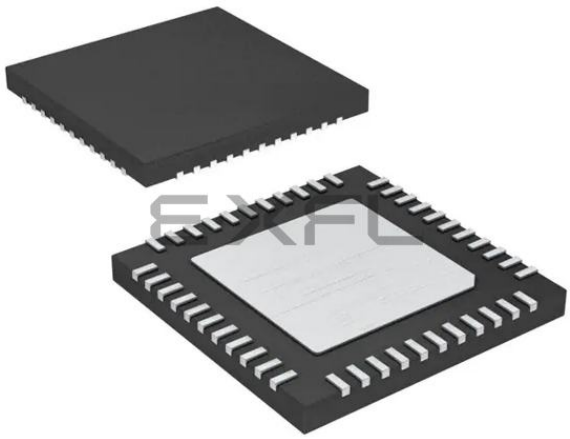
Microchip Technology - DSPIC33EV64GM004-I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm004-i-ml

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(1,2)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit

1 = REPEAT loop is in progress
0 = REPEAT loop is not in progress

bit 3 **N:** MCU ALU Negative bit

1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit

This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = Overflow has not occurred for signed arithmetic

bit 1 **Z:** MCU ALU Zero bit

1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit

1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL3 = 1. User interrupts are disabled when IPL3 = 1.

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

3: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using the bit operations.

TABLE 4-19: NVM REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0728	WR	WREN	WRERR	NVMSIDL	—	—	RPDF	URERR	—	—	—	—	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000
NVMADR	072A	NVMADR<15:0>																0000
NVMADRU	072C	—	—	—	—	—	—	—	—	NVMADRU<23:16>								0000
NVMKEY	072E	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000
NVMSRCADRL	0730	NVMSRCADR<15:1>															0	0000
NVMSRCADRH	0732	—	—	—	—	—	—	—	—	NVMSRCADR<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: SYSTEM CONTROL REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	VREGSF	—	CM	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	Note 1
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	IOLOCK	LOCK	—	CF	—	—	OSWEN	Note 2
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	FRCDIV2	FRCDIV1	FRCDIV0	PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0	0000
PLLFBD	0746	—	—	—	—	—	—	—	PLLDIV<8:0>									0000
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: RCON register Reset values are dependent on the type of Reset.
2: OSCCON register Reset values are dependent on the Configuration fuses.

TABLE 4-21: REFERENCE CLOCK REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
REFOCON	074E	ROON	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2) (CONTINUED)

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler)
11111 = Input divided by 33
•
•
•
00001 = Input divided by 3
00000 = Input divided by 2 (default)

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.

2: This register resets only on a Power-on Reset (POR).

3: DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

4: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 11-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T2CKR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **T2CKR<7:0>:** Assign Timer2 External Clock (T2CK) to the Corresponding RPn pin bits (see Table 11-2 for input pin selection numbers)

10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 15-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits(4)

11111 = Reserved
11110 = Reserved
11101 = Reserved
11100 = CTMU trigger is the source for the capture timer synchronization
11011 = ADC1 interrupt is the source for the capture timer synchronization(5)
11010 = Analog Comparator 3 is the source for the capture timer synchronization(5)
11001 = Analog Comparator 2 is the source for the capture timer synchronization(5)
11000 = Analog Comparator 1 is the source for the capture timer synchronization(5)
10111 = Analog Comparator 5 is the source for the capture timer synchronization(5)
10110 = Analog Comparator 4 is the source for the capture timer synchronization(5)
10101 = Reserved
10100 = Reserved
10011 = Input Capture 4 interrupt is the source for the capture timer synchronization
10010 = Input Capture 3 interrupt is the source for the capture timer synchronization
10001 = Input Capture 2 interrupt is the source for the capture timer synchronization
10000 = Input Capture 1 interrupt is the source for the capture timer synchronization
01111 = GP Timer5 is the source for the capture timer synchronization
01110 = GP Timer4 is the source for the capture timer synchronization
01101 = GP Timer3 is the source for the capture timer synchronization
01100 = GP Timer2 is the source for the capture timer synchronization
01011 = GP Timer1 is the source for the capture timer synchronization
01010 = Reserved
01001 = Reserved
01000 = Input Capture 4 is the source for the capture timer synchronization(6)
00111 = Input Capture 3 is the source for the capture timer synchronization(6)
00110 = Input Capture 2 is the source for the capture timer synchronization(6)
00101 = Input Capture 1 is the source for the capture timer synchronization(6)
00100 = Output Compare 4 is the source for the capture timer synchronization
00011 = Output Compare 3 is the source for the capture timer synchronization
00010 = Output Compare 2 is the source for the capture timer synchronization
00001 = Output Compare 1 is the source for the capture timer synchronization
00000 = Reserved

Note 1: The IC32 bit in both the odd and even ICx must be set to enable Cascade mode.
2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.
3: This bit is set by the selected input source (selected by the SYNCSEL<4:0> bits); it can be read, set and cleared in software.
4: Do not use the ICx module as its own sync or trigger source.
5: This option should only be selected as a trigger source and not as a synchronization source.
6: When the source ICx timer rolls over, then in the next clock cycle, trigger or synchronization occurs.

16.1 Output Compare Control Registers

REGISTER 16-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	—
bit 15							bit 8

R/W-0	U-0	U-0	R/W-0, HSC	R/W-0	R/W-0	R/W-0	R/W-0
ENFLTA	—	—	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Output Compare x Stop in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-10 **OCTSEL<2:0>:** Output Compare x Clock Select bits
111 = Peripheral clock (FP)
110 = Reserved
101 = Reserved
100 = T1CLK is the clock source of the OCx (only the synchronous clock is supported)
011 = T5CLK is the clock source of the OCx
010 = T4CLK is the clock source of the OCx
001 = T3CLK is the clock source of the OCx
000 = T2CLK is the clock source of the OCx

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **ENFLTA:** Output Compare x Fault A Input Enable bit
1 = Output Compare Fault A (OCFA) input is enabled
0 = Output Compare Fault A (OCFA) input is disabled

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **OCFLTA:** PWM Fault A Condition Status bit
1 = PWM Fault A condition on the OCFA pin has occurred
0 = PWM Fault A condition on the OCFA pin has not occurred

bit 3 **TRIGMODE:** Trigger Status Mode Select bit
1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
0 = TRIGSTAT is cleared only by software

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

REGISTER 17-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to the selected Fault input
0 = Leading-Edge Blanking is not applied to the selected Fault input

bit 10 **CLLEBEN:** Current-Limit Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to the selected current-limit input
0 = Leading-Edge Blanking is not applied to the selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when the selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when the selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxH output is high
0 = No blanking when the PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxH output is low
0 = No blanking when the PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxL output is high
0 = No blanking when the PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxL output is low
0 = No blanking when the PWMxL output is low

Note 1: The blanking signal is selected through the BLANKSEL<3:0> bits in the AUXCONx register.

REGISTER 19-3: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3 **S:** I2Cx Start bit
Updated when Start, Reset or Stop is detected; cleared when the I^2C module is disabled, I2CEN = 0.
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Indicates that a Start bit was not detected last

bit 2 **R_W:** Read/Write Information bit (when operating as I^2C slave)
1 = Read: Indicates that the data transfer is output from the slave
0 = Write: Indicates that the data transfer is input to the slave

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive is complete, the I2CxRCV bit is full
0 = Receive is not complete, the I2CxRCV bit is empty

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit is in progress, I2CxTRN is full (8 bits of data)
0 = Transmit is complete, I2CxTRN is empty

REGISTER 19-4: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	MSK<9:8>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
MSK<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **MSK<9:0>:** I2Cx Mask for Address Bit x Select bits
1 = Enables masking for bit x of the incoming message address; bit match is not required in this position
0 = Disables masking for bit x; bit match is required in this position

REGISTER 26-2: CVR2CON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER 2

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0
CVREN	CVROE(1)	—	—	CVRSS	VREFSEL	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CVR6	CVR5	CVR4	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CVREN:** Comparator Voltage Reference Enable bit
1 = Comparator voltage reference circuit is powered on
0 = Comparator voltage reference circuit is powered down

bit 14 **CVROE:** Comparator Voltage Reference Output Enable (CVREF2O Pin) bit(1)
1 = Voltage level is output on the CVREF2O pin
0 = Voltage level is disconnected from the CVREF2O pin

bit 13-12 **Unimplemented:** Read as '0'

bit 11 **CVRSS:** Comparator Voltage Reference Source Selection bit
1 = Comparator reference source, CVRSRC = CVREF+ – AVSS
0 = Comparator reference source, CVRSRC = AVDD – AVSS

bit 10 **VREFSEL:** Voltage Reference Select bit
1 = Comparator Reference Source 2 (CVR2) provides inverting input voltage when VREFSEL (CVR1CON<10>) = 0
0 = Comparator Reference Source 1 (CVR1) provides inverting input voltage when VREFSEL (CVR1CON<10>) = 0

bit 9-7 **Unimplemented:** Read as '0'

bit 6-0 **CVR<6:0>:** Comparator Voltage Reference Value Selection bits
1111111 = 127/128 x VREF input voltage
•
•
•
0000000 = 0.0 volts

Note 1: CVROE (CVR2CON<14>) is not available on the 28-pin devices.

27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EVXXXGM00X/10X family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EVXXXGM00X/10X family devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to ensure that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '1111 1111 1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

TABLE 27-2: dsPIC33EVXXXGM00X/10X CONFIGURATION BITS DESCRIPTION

Bit Field	Register	Description
BWRP	FSEC	Boot Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
BSS<1:0>	FSEC	Boot Segment Code Flash Protection Level bits 11 = No protection (other than BWRP write protection) 10 = Standard security 0x = High security
BSEN	FSEC	Boot Segment Control bit 1 = No Boot Segment 0 = Boot Segment size is determined by BSLIM<12:0>
GWRP	FSEC	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
GSS<1:0>	FSEC	General Segment Code Flash Protection Level bits 11 = No protection (other than GWRP write protection) 10 = Standard security 0x = High security
CWRP	FSEC	Configuration Segment Write-Protect bit 1 = Configuration Segment is not write-protected 0 = Configuration Segment is write-protected
CSS<2:0>	FSEC	Configuration Segment Code Flash Protection Level bits 111 = No protection (other than CWRP write protection) 110 = Standard security 10x = Enhanced security 0xx = High security
AIVTDIS	FSEC	Alternate Interrupt Vector Table Disable bit 1 = Disables AIVT 0 = Enables AIVT
BSLIM<12:0>	FBSLIM	Boot Segment Code Flash Page Address Limit bits Contains the page address of the first active General Segment page. The value to be programmed is the inverted page address, such that programming additional '0's can only increase the Boot Segment size. For example, 0x1FFD = 2 pages or 1024 instruction words.
FNOSC<2:0>	FOSCSEL	Initial Oscillator Source Selection bits 111 = Internal Fast RC (FRC) Oscillator with Postscaler 110 = Internal Fast RC (FRC) Oscillator with Divide-by-16 101 = LPRC Oscillator 100 = Reserved 011 = Primary (XT, HS, EC) Oscillator with PLL 010 = Primary (XT, HS, EC) Oscillator 001 = Internal Fast RC (FRC) Oscillator with PLL 000 = FRC Oscillator
$\overline{\text{IESO}}$	FOSCSEL	Two-Speed Oscillator Start-up Enable bit 1 = Starts up device with FRC, then automatically switches to the user-selected oscillator source when ready 0 = Starts up device with user-selected oscillator source
POSCMD<1:0>	FOSC	Primary Oscillator Mode Select bits 11 = Primary Oscillator is disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
46	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
47	MOV	MOV	f,Wn	Move f to Wn	1	1	None
		MOV	f	Move f to f	1	1	None
		MOV	f,WREG	Move f to WREG	1	1	None
		MOV	#lit16,Wn	Move 16-bit literal to Wn	1	1	None
		MOV.b	#lit8,Wn	Move 8-bit literal to Wn	1	1	None
		MOV	Wn,f	Move Wn to f	1	1	None
		MOV	Wso,Wdo	Move Ws to Wd	1	1	None
		MOV	WREG,f	Move WREG to f	1	1	None
		MOV.D	Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		MOV.D	Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
48	MOVPAG	MOVPAG	#lit10,DSRPAG	Move 10-bit literal to DSRPAG	1	1	None
		MOVPAG	#lit9,DSWPAG	Move 9-bit literal to DSWPAG	1	1	None
		MOVPAG	#lit8,TBLPAG	Move 8-bit literal to TBLPAG	1	1	None
		MOVPAGW	Ws, DSRPAG	Move Ws<9:0> to DSRPAG	1	1	None
		MOVPAGW	Ws, DSWPAG	Move Ws<8:0> to DSWPAG	1	1	None
		MOVPAGW	Ws, TBLPAG	Move Ws<7:0> to TBLPAG	1	1	None
49	MOVSAC	MOVSAC	Acc,Wx,Wxd,Wy,Wyd,AWB	Prefetch and store accumulator	1	1	None
50	MPY	MPY	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
51	MPY.N	MPY.N	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	-(Multiply Wm by Wn) to Accumulator	1	1	None
52	MSC	MSC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Maximum MIPS
			dsPIC33EVXXXGM00X/10X Family
I-Temp	4.5V to 5.5V(1,2)	-40°C to +85°C	70
E-Temp	4.5V to 5.5V(1,2)	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, op amp/comparator and comparator voltage reference will have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: When BOR is enabled, the device will work from 4.7V to 5.5V.

Note 1: Customer operating voltage range is specified as: 4.5V to 5.5V.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices:					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices:					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin QFN, 9x9x0.9 mm	θJA	28.0	—	°C/W	**1**
Package Thermal Resistance, 64-Pin TQFP, 10x10x1 mm	θJA	48.3	—	°C/W	**1**
Package Thermal Resistance, 44-Pin QFN, 8x8 mm	θJA	29.0	—	°C/W	**1**
Package Thermal Resistance, 44-Pin TQFP, 10x10x1 mm	θJA	49.8	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN-S, 6x6x0.9 mm	θJA	30.0	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC, 7.50 mm	θJA	69.7	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP, 5.30 mm	θJA	71.0	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP, 300 mil	θJA	60.0	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8.0	MHz	ECPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	120	—	340	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	ms	
OS53	DCLK	CLKO Stability (Jitter)(2)	-3	0.5	3	%	

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This jitter specification is based on clock cycle-by-clock cycle measurements. To get the effective jitter for individual time bases or communication clocks used by the application, use the following formula:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{FOSC}{\text{Time Base or Communication Clock}}}}$$

For example, if FOSC = 120 MHz and the SPI bit rate = 10 MHz, the effective jitter is as follows:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{120}{10}}} = \frac{DCLK}{\sqrt{12}} = \frac{DCLK}{3.464}$$

TABLE 30-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**	
Internal FRC Accuracy @ FRC Frequency = 7.37 MHz(1)							
F20a	FRC	-1	0.5	+1	%	-40°C ≤ TA ≤ +85°C	VDD = 4.5-5.5V
F20b	FRC	-2	1	+2	%	-40°C ≤ TA ≤ +125°C	VDD = 4.5-5.5V

Note 1: Frequency calibrated at +25°C and 5.0V. TUN<5:0> bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**	
LPRC @ 32.768 kHz(1)							
F21a	LPRC	-15	5	+15	%	-40°C ≤ TA ≤ +85°C	VDD = 4.5-5.5V
F21b	LPRC	-30	10	+30	%	-40°C ≤ TA ≤ +125°C	VDD = 4.5-5.5V

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 30-25: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

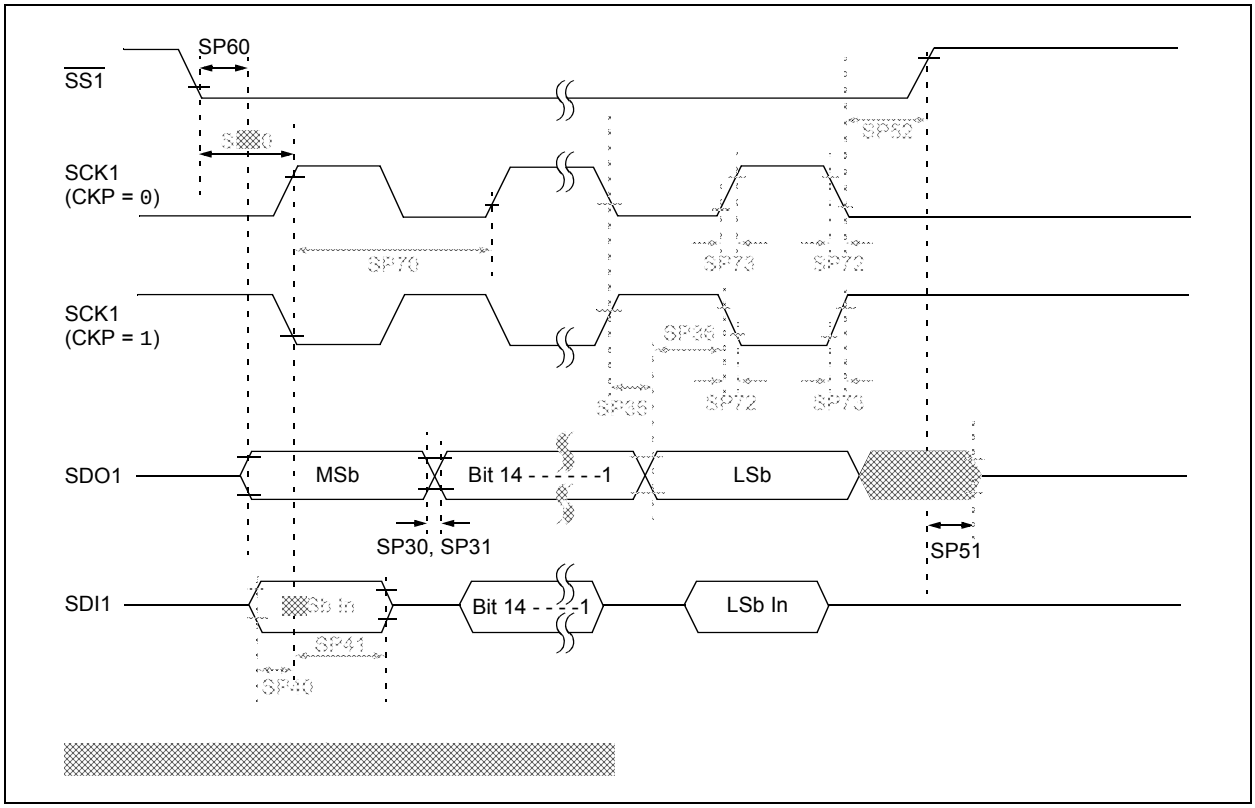


TABLE 30-55: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (12-Bit Mode)							
AD20a	Nr	Resolution	12 data bits			bits	
AD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD23a	GERR	Gain Error	-10	4	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD24a	EOFF	Offset Error	-10	1.75	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5.5V
AD25a	—	Monotonicity(2)	—	—	—	—	Guaranteed
Dynamic Performance (12-Bit Mode)							
AD30a	THD	Total Harmonic Distortion	—	—	-75	dB	
AD31a	SINAD	Signal to Noise and Distortion	68.5	69.5	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range	80	—	—	dB	
AD33a	FNYQ	Input Signal Bandwidth	—	—	250	kHz	
AD34a	ENOB	Effective Number of Bits	11.09	11.3	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: The conversion result never decreases with an increase in the input voltage.

TABLE 30-58: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(4)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	75	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	12	—	TAD	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	Using simultaneous sampling
AD57a	TSAMP	Sample Time When Sampling Any ANx Input	2	—	—	TAD	
AD57b	TSAMP	Sample Time When Sampling the Op Amp Outputs	4	—	—	TAD	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2	—	3	TAD	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2	—	3	TAD	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2)	—	0.5	—	TAD	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2)	—	—	20	μs	See **Note 3**

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (ADxCON1<15>) = 1). During this time, the ADC result is indeterminate.

4: These parameters are characterized but not tested in manufacturing.

TABLE 30-59: DMA MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DM1	DMA Byte/Word Transfer Latency	1 TCY(2)	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because DMA transfers use the CPU data bus, this time is dependent on other functions on the bus.

31.1 High-Temperature DC Characteristics

TABLE 31-1: OPERATING MIPS vs. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33EVXXXGM00X/10X Family
HDC5	4.5V to 5.5V(1,2)	-40°C to +150°C	40

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules, such as the ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Device functionality is tested but is not characterized. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: When BOR is enabled, the device will work from 4.7V to 5.5V.

TABLE 31-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High-Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 31-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	Symbol	Characteristic	Min.	Typ.(1)	Max.	Units	Conditions
Operating Voltage							
HDC10	VDD	**Supply Voltage(3)**	VBOR	—	5.5	V	
HDC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	
HDC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
HDC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	1.0	—	—	V/ms	0V-5.0V in 5 ms
HDC18	VCORE	**VDD Core** Internal Regulator Voltage	1.62	1.8	1.98	V	Voltage is dependent on load, temperature and VDD

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

2: This is the limit to which VDD may be lowered without losing RAM data.

3: VDD voltage must remain at VSS for a minimum of 200 μs to ensure POR.

31.2 AC Characteristics and Timing Parameters

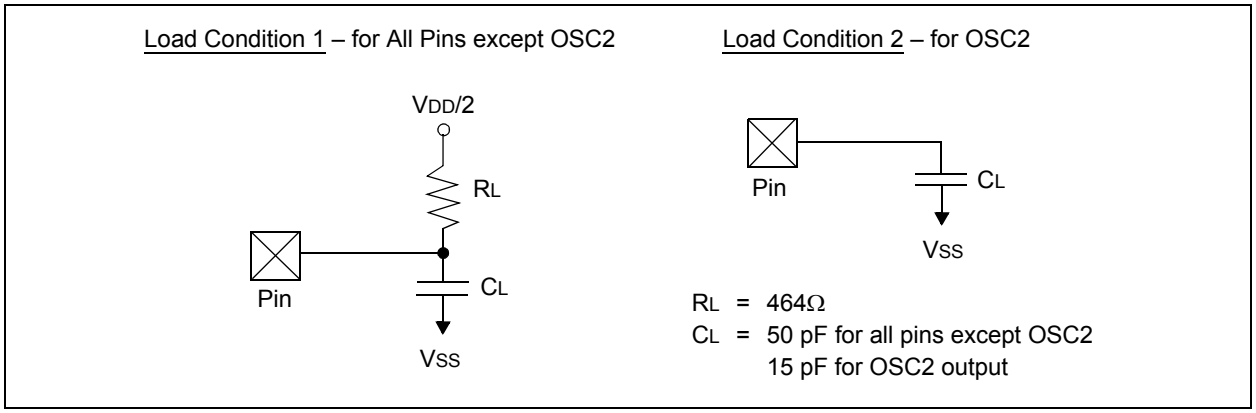
The information contained in this section defines the dsPIC33EVXXXGM00X/10X family AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-12: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

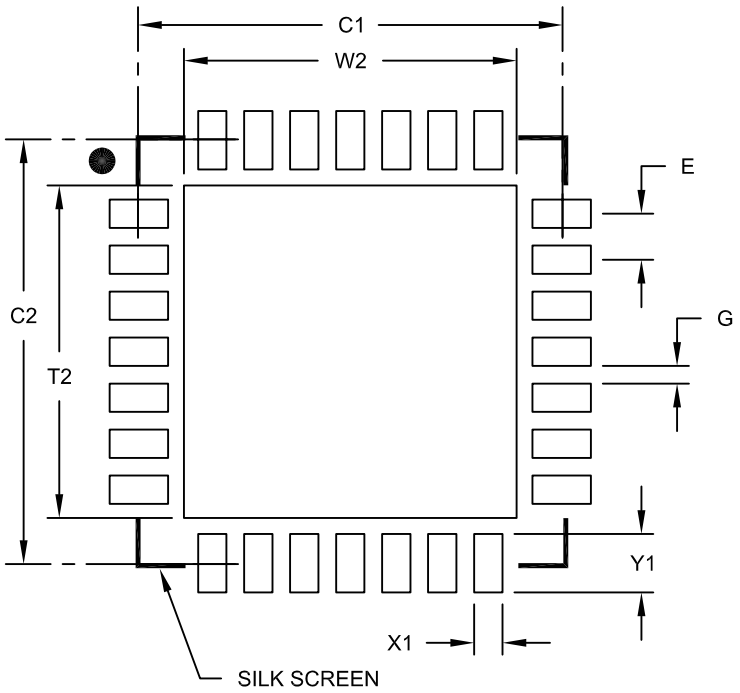
AC CHARACTERISTICS	**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A